

Title (en)

Composite contact, vacuum switch and method for manufacturing composite contact

Title (de)

Kontakt aus Verbundwerkstoff, Vakuumschalter und Herstellungsverfahren des Kontaktes

Title (fr)

Conact en matériaux composites, disjoncteur à vide et procédé de fabrication du contact

Publication

**EP 1580779 A1 20050928 (EN)**

Application

**EP 05102282 A 20050322**

Priority

- JP 2004082961 A 20040322
- JP 2004258155 A 20040906

Abstract (en)

A composite contact including a first layer composed of a Cu-Cr mixture wherein powder or granular Cr with an average particle diameter of 0.1 to 150  $\mu\text{m}$  and powder or granular Cu with an average particle diameter of 0.1 to 150  $\mu\text{m}$  are mixed at a rate of 15 to 60 wt% of Cr and the remainder of Cu, and a second layer composed of Cu. The first layer and the second layer are united with each other, while Cu of the first layer enters the second layer within a range from 20  $\mu\text{m}$  to 100  $\mu\text{m}$  from a boundary surface between the first layer and the second layer and Cu in the second layer enters the first layer within a range from 20  $\mu\text{m}$  to 100  $\mu\text{m}$  from the boundary surface.

IPC 1-7

**H01H 1/02**

IPC 8 full level

**H01H 1/02** (2006.01)

CPC (source: EP)

**H01H 1/0206** (2013.01)

Citation (search report)

- [A] DE 19822469 A1 19981126 - HITACHI LTD [JP]
- [A] EP 0846515 A1 19980610 - LOUIS RENNER GMBH [DE]
- [A] EP 0469578 A2 19920205 - MEIDENSHA ELECTRIC MFG CO LTD [JP], et al

Designated contracting state (EPC)

DE FR

DOCDB simple family (publication)

**EP 1580779 A1 20050928; EP 1580779 B1 20100505**; CN 100358063 C 20071226; CN 1674180 A 20050928; DE 602005021009 D1 20100617

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**EP 05102282 A 20050322**; CN 200510056186 A 20050322; DE 602005021009 T 20050322